

PSMN011-100YSF

NextPower 100V, 10.9 m Ω N-channel MOSFET in LFPAK56 package

18 March 2019

Product data sheet

1. General description

NextPower 100V standard level gate drive MOSFET. Qualified to 175 °C and recommended for industrial & consumer applications.

2. Features and benefits

- Low Q_{rr} for higher efficiency and lower spiking
- Qualified to 175 °C
- Low Q_G x R_{DSon} FOM for high efficiency switching applications
- Strong avalanche energy rating (E_{as})
- Avalanche rated and 100% tested
- Ha-free and RoHS compliant LFPAK56 package
- Wave-solderable LFPAK56 package
- Low-stress LFPAK leadframe for high-reliability applications

3. Applications

- · Synchronous rectifier in AC-DC and DC-DC
- BLDC motor control
- USB-PD and mobile fast-charge adapters
- · LED lighting
- · Full-bridge and half-bridge applications
- · Flyback and resonant topologies

4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
V _{DS}	drain-source voltage	25 °C ≤ T _j ≤ 175 °C	-	-	100	V
I _D	drain current	V _{GS} = 10 V; T _{mb} = 25 °C; <u>Fig. 2</u>	-	-	79.5	Α
P _{tot}	total power dissipation	T _{mb} = 25 °C; <u>Fig. 1</u>	-	-	152	W
Tj	junction temperature		-55	-	175	°C
Static char	acteristics					
R _{DSon}	drain-source on-state resistance	V_{GS} = 10 V; I_D = 20 A; T_j = 25 °C; Fig. 12	-	8.8	10.9	mΩ
		V_{GS} = 10 V; I_D = 20 A; T_j = 100 °C; Fig. 13	-	13.9	17.7	mΩ
Dynamic cl	haracteristics					
Q _{GD}	gate-drain charge	I _D = 20 A; V _{DS} = 50 V; V _{GS} = 10 V;	-	8.1	-	nC
Q _{G(tot)}	total gate charge	Fig. 14; Fig. 15	-	34.3	-	nC
Avalanche	ruggedness			1	-	



Symbol	Parameter	Conditions		Min	Тур	Max	Unit	
E _{DS(AL)S}	non-repetitive drain- source avalanche energy	I_D = 27 A; $V_{sup} \le 100$ V; R_{GS} = 50 Ω; V_{GS} = 10 V; $T_{j(init)}$ = 25 °C; unclamped; Fig. 4	[1]	-	-	173	mJ	
Source-drain d	Source-drain diode							
Q _r	recovered charge	$I_S = 20 \text{ A}; dI_S/dt = -100 \text{ A/}\mu\text{s}; V_{GS} = 0 \text{ V}; V_{DS} = 50 \text{ V}; Fig. 18$		-	36.5	-	nC	

^[1] Protected by 100% test

5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	S	source	mb	D
2	S	source	<u> </u>	
3	S	source		G—(FA)
4	G	gate		mbb076 S
mb	D	mounting base; connected to drain	1 2 3 4 LFPAK56; Power- SO8 (SOT669)	

6. Ordering information

Table 3. Ordering information

Type number	ype number Package					
	Name	Description	Version			
PSMN011-100YSF	LFPAK56; Power-SO8	plastic, single-ended surface-mounted package; 4 terminals	SOT669			

7. Marking

Table 4. Marking codes

Type number	Marking code
PSMN011-100YSF	11FS10Y

8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	IV	lin Ma	ах	Unit
V _{DS}	drain-source voltage	25 °C ≤ T _j ≤ 175 °C	-	10	00	V
V_{DGR}	drain-gate voltage	25 °C ≤ T_j ≤ 175 °C; R_{GS} = 20 kΩ	-	10	00	V
V_{GS}	gate-source voltage		-2	20 20)	V
P _{tot}	total power dissipation	T _{mb} = 25 °C; <u>Fig. 1</u>	-	15	52	W
I _D	drain current	V _{GS} = 10 V; T _{mb} = 25 °C; <u>Fig. 2</u>	-	79	9.5	Α
		V _{GS} = 10 V; T _{mb} = 100 °C; <u>Fig. 2</u>	-	56	5.2	Α
I _{DM}	peak drain current	pulsed; $t_p \le 10 \mu s$; $T_{mb} = 25 °C$; Fig. 3	-	31	18	Α

Symbol	Parameter	Conditions		Min	Max	Unit
T _{stg}	storage temperature			-55	175	°C
Tj	junction temperature			-55	175	°C
$T_{sld(M)}$	peak soldering temperature			-	260	°C
Source-drain di	ode					
Is	source current	T _{mb} = 25 °C		-	79.5	А
I _{SM}	peak source current	pulsed; $t_p \le 10 \mu s$; $T_{mb} = 25 ^{\circ}C$		-	318	А
Avalanche rugg	edness				•	
E _{DS(AL)S}	non-repetitive drain- source avalanche energy	I_D = 27 A; $V_{sup} \le 100$ V; R_{GS} = 50 Ω; V_{GS} = 10 V; $T_{j(init)}$ = 25 °C; unclamped; Fig. 4	[1]	-	173	mJ
I _{AS}	non-repetitive avalanche current	V_{sup} = 100 V; V_{GS} = 10 V; $T_{j(init)}$ = 25 °C; R_{GS} = 50 Ω	[1]	-	27	A

[1] Protected by 100% test

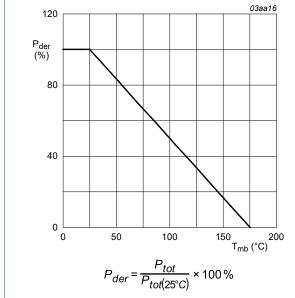


Fig. 1. Normalized total power dissipation as a function of mounting base temperature

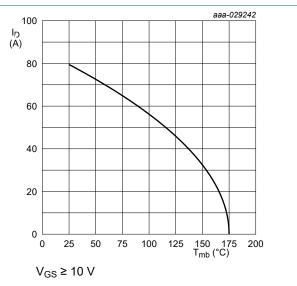
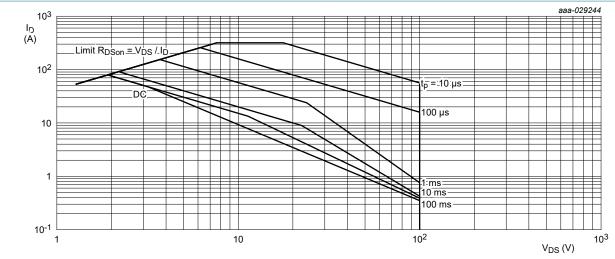
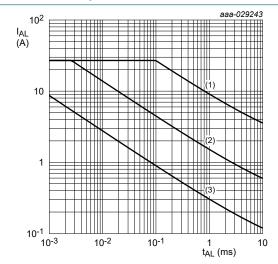


Fig. 2. Continuous drain current as a function of mounting base temperature



T_{mb} = 25 °C; I_{DM} is a single pulse

Fig. 3. Safe operating area; continuous and peak drain currents as a function of drain-source voltage



(1) $T_{j \text{ (init)}}$ = 25 °C; (2) $T_{j \text{ (init)}}$ = 150 °C; (3) Repetitive Avalanche

Fig. 4. Avalanche rating; avalanche current as a function of avalanche time

9. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
R _{th(j-mb)}	thermal resistance from junction to mounting base	Fig. 5	-	0.87	0.99	K/W
R _{th(j-a)} thermal resistance from junction to ambient	Fig. 6	-	42	-	K/W	
	Fig. 7	-	85	-	K/W	

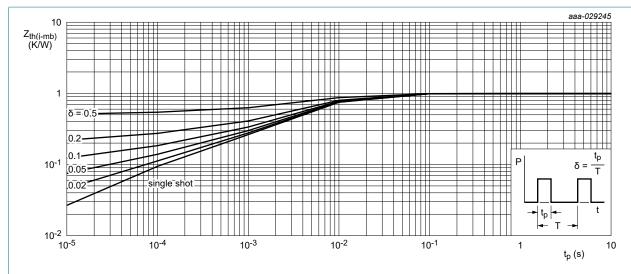
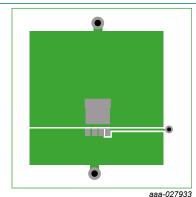
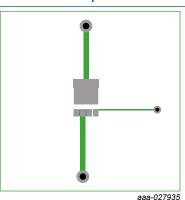


Fig. 5. Transient thermal impedance from junction to mounting base as a function of pulse duration



Copper square 25.4 mm x 25.4 mm; 70 μ m thick on FR4 board

Fig. 6. PCB layout for resistance from junction to ambient



70 µm thick copper on FR4 board

Fig. 7. PCB layout with minimum footprint for thermal resistance from junction to ambient

10. Characteristics

Table 7. Characteristics

Symbol	Parameter	Conditions	N	lin	Тур	Max	Unit
Static charac	cteristics		'		'	'	'
V _{(BR)DSS}	drain-source	I _D = 250 μA; V _{GS} = 0 V; T _j = 25 °C	1	00	-	-	V
	breakdown voltage	I _D = 250 μA; V _{GS} = 0 V; T _j = -55 °C	9	0	-	-	V
V _{GS(th)}	gate-source threshold	$I_D = 1 \text{ mA}; V_{DS} = V_{GS}; T_j = -55 \text{ °C}$	-		3.6	-	V
	voltage	$I_D = 1 \text{ mA}; V_{DS} = V_{GS}; T_j = 175 \text{ °C}$	-		1.9	-	V
		$I_D = 1 \text{ mA}; V_{DS} = V_{GS}; T_j = 25 \text{ °C}; Fig. 11$	2		3.1	4	V
$\Delta V_{GS(th)}/\Delta T$	gate-source threshold voltage variation with temperature	25 °C ≤ T _j ≤ 175 °C	-		-7.9	-	mV/K
I _{DSS}	drain leakage current	V _{DS} = 100 V; V _{GS} = 0 V; T _j = 25 °C	-		0.02	5	μA
		V _{DS} = 100 V; V _{GS} = 0 V; T _j = 125 °C	-		-	100	μA
I _{GSS}	gate leakage current	V _{GS} = 20 V; V _{DS} = 0 V; T _j = 25 °C	-		5	100	nA
		V _{GS} = -20 V; V _{DS} = 0 V; T _j = 25 °C	-		5	100	nA

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
R _{DSon}	drain-source on-state resistance	$V_{GS} = 10 \text{ V}; I_D = 20 \text{ A}; T_j = 25 \text{ °C};$ Fig. 12	-	8.8	10.9	mΩ
		$V_{GS} = 7 \text{ V}; I_D = 20 \text{ A}; T_j = 25 \text{ °C}; Fig. 12$	-	10.2	15.2	mΩ
		V_{GS} = 10 V; I_D = 20 A; T_j = 100 °C; Fig. 13	-	13.9	17.7	mΩ
		V_{GS} = 10 V; I_{D} = 20 A; T_{j} = 175 °C; Fig. 13	-	20	25.5	mΩ
R _G	gate resistance	f = 1 MHz; T _j = 25 °C	-	1.8	-	Ω
Dynamic ch	naracteristics					'
Q _{G(tot)}	total gate charge	I _D = 20 A; V _{DS} = 50 V; V _{GS} = 10 V; Fig. 14; Fig. 15	-	34.3	-	nC
		I _D = 0 A; V _{DS} = 0 V; V _{GS} = 10 V	-	16.4	-	nC
Q _{GS}	gate-source charge	I _D = 20 A; V _{DS} = 50 V; V _{GS} = 10 V;	-	10.6	-	nC
Q _{GS(th)}	pre-threshold gate- source charge	Fig. 14; Fig. 15	-	6.4	-	nC
Q _{GS(th-pl)}	post-threshold gate- source charge		-	4.2	-	nC
Q _{GD}	gate-drain charge		-	8.1	-	nC
V _{GS(pl)}	gate-source plateau voltage	I _D = 20 A; V _{DS} = 50 V; <u>Fig. 14</u> ; <u>Fig. 15</u>	-	4.9	-	V
C _{iss}	input capacitance	V _{DS} = 50 V; V _{GS} = 0 V; f = 1 MHz;	-	2258	-	pF
C _{oss}	output capacitance	T _j = 25 °C; <u>Fig. 16</u>	-	395	-	pF
C _{rss}	reverse transfer capacitance		-	21	-	pF
t _{d(on)}	turn-on delay time	$V_{DS} = 50 \text{ V}; R_L = 2.5 \Omega; V_{GS} = 10 \text{ V};$	-	10.2	-	ns
t _r	rise time	$R_{G(ext)} = 5 \Omega; T_j = 25 ^{\circ}C$	-	12.1	-	ns
t _{d(off)}	turn-off delay time		-	21.3	-	ns
t _f	fall time		-	12.8	-	ns
Source-drai	in diode			<u> </u>	1	1
V _{SD}	source-drain voltage	$I_S = 20 \text{ A}; V_{GS} = 0 \text{ V}; T_j = 25 ^{\circ}\text{C}; Fig. 17$	-	0.85	1.2	V
t _{rr}	reverse recovery time	$I_S = 20 \text{ A}; dI_S/dt = -100 \text{ A/}\mu\text{s}; V_{GS} = 0 \text{ V};$	-	38.4	-	ns
Q _r	recovered charge	V _{DS} = 50 V; <u>Fig. 18</u>	-	36.5	-	nC
		1	<u> </u>			

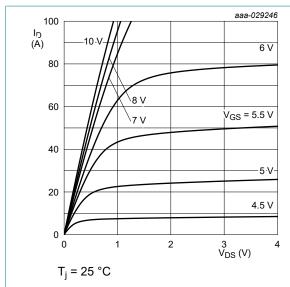


Fig. 8. Output characteristics; drain current as a function of drain-source voltage; typical values

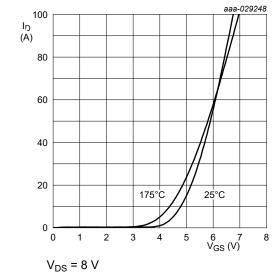


Fig. 10. Transfer characteristics; drain current as a function of gate-source voltage; typical values

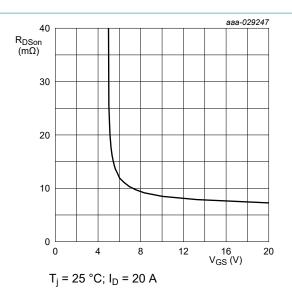


Fig. 9. Drain-source on-state resistance as a function of gate-source voltage; typical values

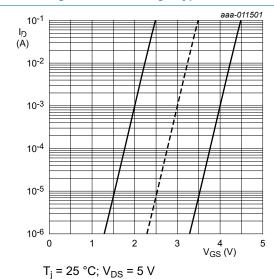


Fig. 11. Sub-threshold drain current as a function of gate-source voltage

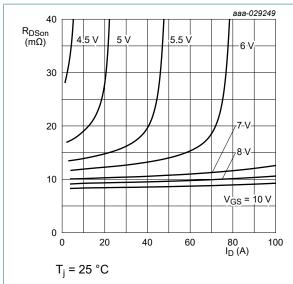


Fig. 12. Drain-source on-state resistance as a function of drain current; typical values

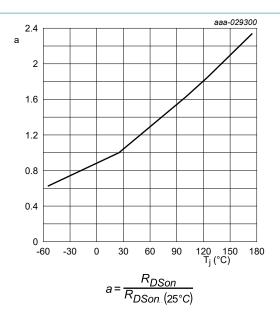


Fig. 13. Normalized drain-source on-state resistance factor as a function of junction temperature

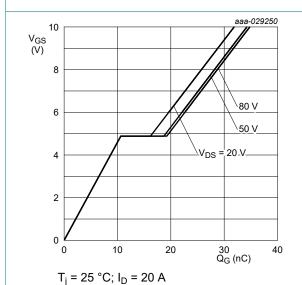


Fig. 14. Gate-source voltage as a function of gate charge; typical values

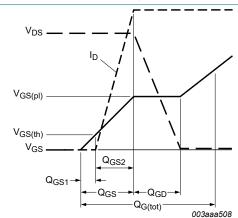


Fig. 15. Gate charge waveform definitions

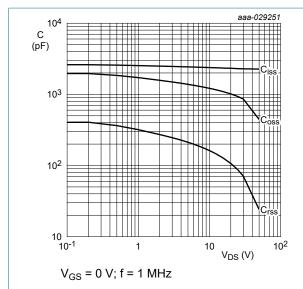
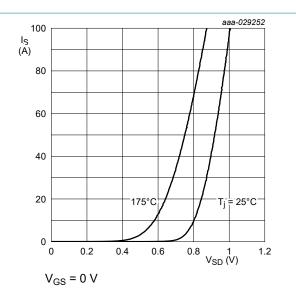


Fig. 16. Input, output and reverse transfer capacitances | Fig. 17. Source-drain (diode forward) current as a as a function of drain-source voltage; typical values



function of source-drain (diode forward) voltage; typical values

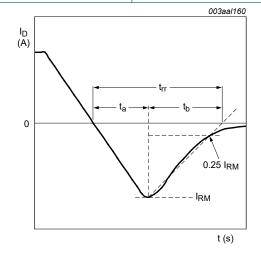
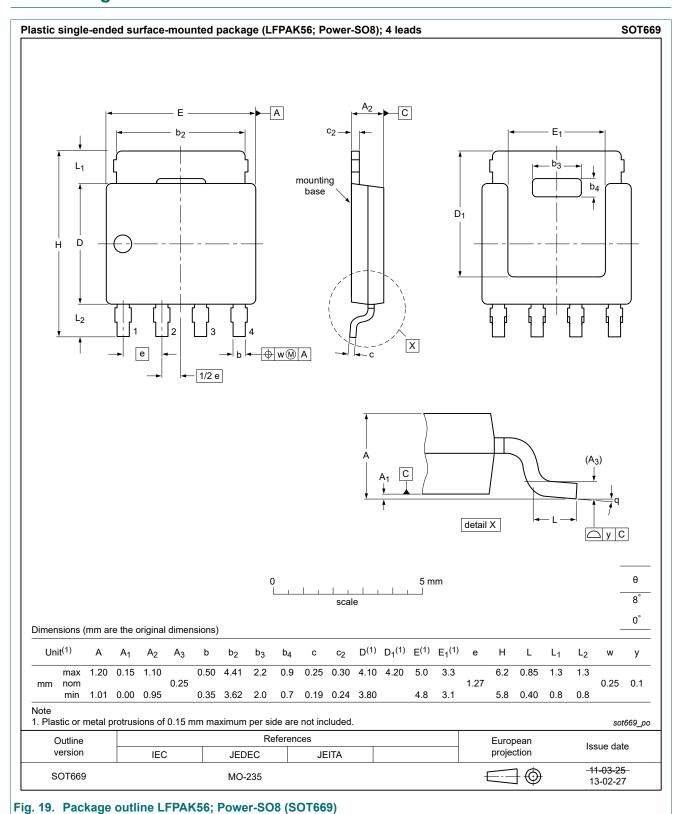
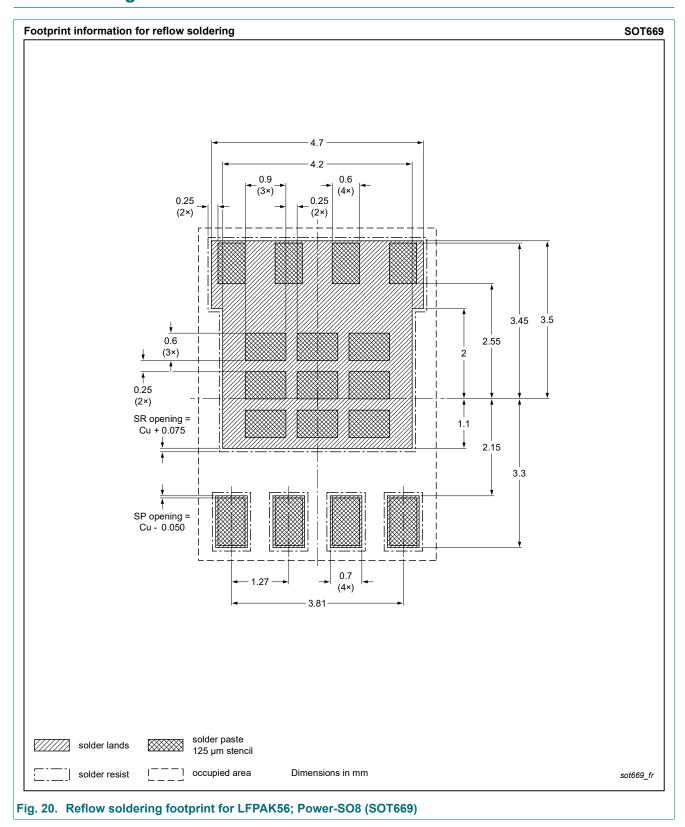


Fig. 18. Reverse recovery timing definition

11. Package outline



12. Soldering



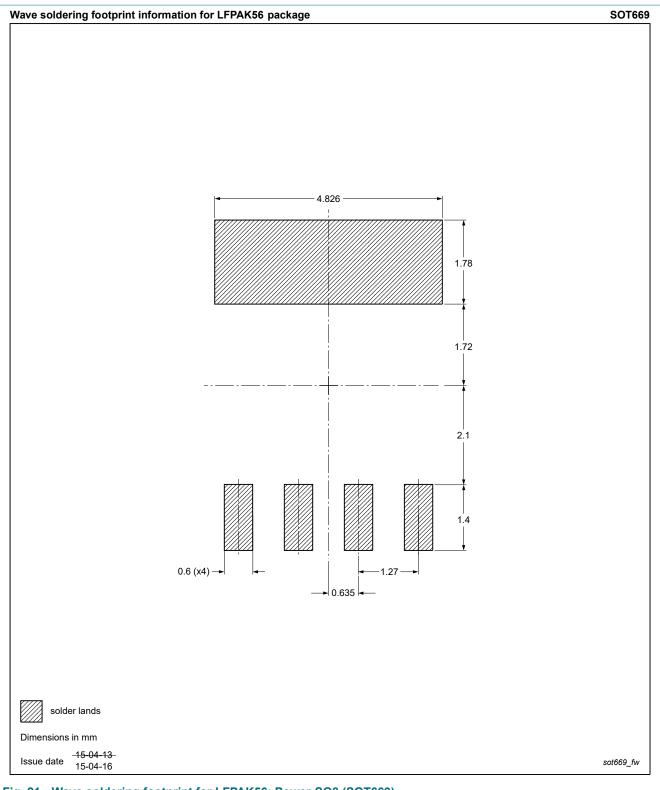


Fig. 21. Wave soldering footprint for LFPAK56; Power-SO8 (SOT669)

12 / 14

13. Legal information

Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

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Contents

1.	General description	1
2.	Features and benefits	1
3.	Applications	1
4.	Quick reference data	1
5.	Pinning information	2
6.	Ordering information	2
7.	Marking	2
8.	Limiting values	2
	Thermal characteristics	
10.	. Characteristics	5
11.	Package outline	10
12.	Soldering	11
	Legal information	

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14 / 14

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«JONHON» (основан в 1970 г.)

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(Применяются в военной, авиационной, аэрокосмической, морской, железнодорожной, горно- и нефтедобывающей отраслях промышленности)

«**FORSTAR**» (основан в 1998 г.)

ВЧ соединители, коаксиальные кабели, кабельные сборки и микроволновые компоненты:

(Применяются в телекоммуникациях гражданского и специального назначения, в средствах связи, РЛС, а так же военной, авиационной и аэрокосмической отраслях промышленности).



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